Absolute Maximum Rating Table 1.

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply voltage	45	V
-1	DC ground pin reverse current	-250	mA
-I _{GND}	TRAN Ground pin reverse current (pulse duration < 1ms)	-6	Α
I _{OUT}	DC Output current	Internally limited	А
-l _{OUT}	Reverse DC output current	-2	А
I _{IN}	DC Input current	± 10	mA
V _{IN}	Input voltage range	-3/+V _{CC}	V
V _{ESD}	Electrostatic discharge (R = 1.5KW; C = 100pF)	2000	V
P _{TOT}	Power dissipation at T _c = 25°C	96	W
L _{MAX}	Max inductive load (V_{CC} = 24V, R_{LOAD} = 48 Ω , T_A = 100°C)	2	Н
TJ	Junction operating temperature	Internally limited	°C
T _C	Case operating temperature	Internally limited	°C
T _{STG}	Storage Temperature	-55 to 150	°C

Pin Definitions and Functions Table 2.

		16
Definitions and F	unctions	
Symbol	Function	on Allo
V _{CC}	Positive power supply voltage	2100
V _{CC}	Positive power supply voltage	N.
NC	Not connected)
Input 1	Input of channel 1	
Input 2	Input of channel 2	
Input 3	Input of channel 3	
Input 4	Input of channel 4	
Input 5	Input of channel 5	
Input 6	Input of channel 6	
Input 7	Input of channel 7	
Input 8	Input of channel 8	
NC	Not connected	
GND	Logic ground	
STATUS	Common open source diagnostic for over	er-temperature
Output 8	High-Side output of channel 8	
Output 7	High-Side output of channel 7	
Output 6	High-Side output of channel 6	
Output 5	High-Side output of channel 5	
Output 4	High-Side output of channel 4	
Output 3	High-Side output of channel 3	
Output 2	High-Side output of channel 2	
Output 1	High-Side output of channel 1	
	Symbol VCC VCC NC Input 1 Input 2 Input 3 Input 4 Input 5 Input 6 Input 7 Input 8 NC GND STATUS Output 8 Output 7 Output 6 Output 5 Output 4 Output 5 Output 2	V _{CC} Positive power supply voltage V _{CC} Positive power supply voltage NC Not connected Input 1 Input of channel 1 Input 2 Input of channel 2 Input 3 Input of channel 3 Input 4 Input of channel 4 Input 5 Input of channel 5 Input 6 Input of channel 7 Input 8 Input of channel 8 NC Not connected GND Logic ground STATUS Common open source diagnostic for over Output 8 High-Side output of channel 7 Output 6 High-Side output of channel 6 Output 7 High-Side output of channel 7 Output 6 High-Side output of channel 6 Output 7 High-Side output of channel 6 Output 3 High-Side output of channel 3 Output 2 High-Side output of channel 3

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Figure 1. Connection Diagram (Top View)

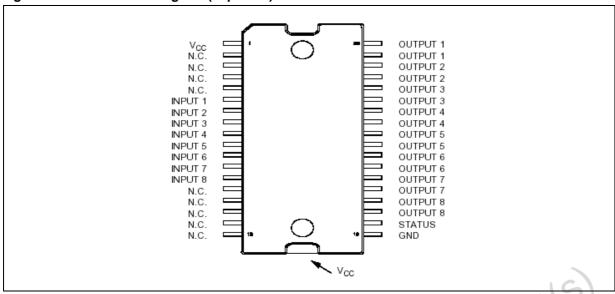
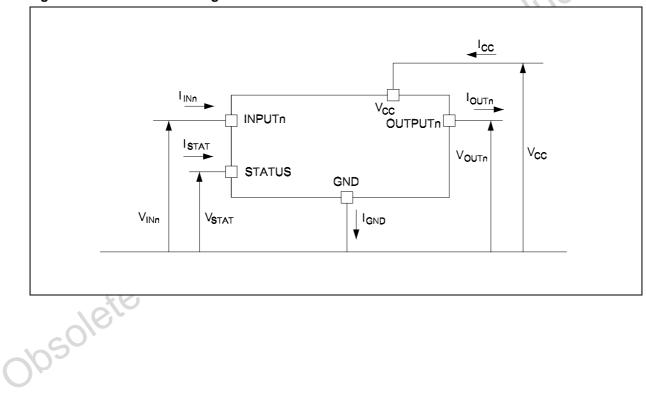


Figure 2. Current and Voltage Conventions



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Table 3. Thermal data

Symbol	Parameter	Value	Unit	
R _{thJC}	Thermal resistance junction-case	Max	1.3	°C/W
R _{thJA}	Thermal resistance junction-ambient Note:1	Max	50	°C/W

Note: 1. When mounted on FR4 printed circuit board with 0.5cm² of copper area (at least 35µ think) connected to all TAB pins.

Electrical Characteristics (10.5V < V_{CC} < 32V; -40°C < T_{J} < 100°C; unless otherwise specified)

Table 4. Power Section

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{CC}	Operating supply voltage		10.5		45	V
V _{USD}	Undervoltage shutdown		7		10.5	V
R _{ON}	On state resistance	$I_{OUT} = 0.5A; T_J = 25^{\circ}C$ $I_{OUT} = 0.5A;$		150	185 280	$m\Omega$
I _S	Supply current	OFF state; V _{CC} = 24V; T _{CASE} = 25°C ON state(all channels ON); V _{CC} = 24V T _{CASE} = 100°C	01	og _{//}	150 12	μA mA
I _{LGND}	Output current at turn-off	$V_{CC} = V_{STAT} = V_{IN} = V_{GND} = 24V$ $V_{OUT} = 0V$			1	mA
I _{L(off)}	OFF state output current	$V_{IN} = V_{OUT} = 0V_{;}$	0		5	μΑ
V _{OUT(off)}	OFF state output voltage	$V_{IN} = 0V$, $I_{OUT} = 0A$			3	V
t _{d(Vccon)}	Power-on delay time from V _{CC} rising edge	Figure 6.		1		ms

Table 5. Switching (V_{CC} = 24V)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{ON}	Turn-on time	$R_L = 48\Omega$ from 80% V_{OUT} Figure 5.		50	100	μs
t _{OFF}	Turn-off time	$R_L = 48\Omega$ to 10% V_{OUT} Figure 5.		75	150	μs
dV _{OUT/}	Turn-on voltage slope	$R_L = 48\Omega$ from $V_{OUT} = 2.4V$ to $V_{OUT} = 19.2V$ <i>Figure 5.</i>		0.7		V/µs
dV _{OUT/}	Turn-off voltage slope	$R_L = 48\Omega$ from $V_{OUT} = 21.6V$ to $V_{OUT} = 2.4V$ <i>Figure 5.</i>		1.5		V/µs

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Table 6. Input Pin

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{INL}	Input low level				V _{CC} /2-1	V
I _{INL}	Low level input current	V _{IN} = V _{CC} / 2 - 1V	80			μΑ
V _{INH}	Input high level		V _{CC} /2+1			V
I _{INH}	High level input current	V _{IN} = V _{CC} / 2 + 1V		150	260	μΑ
V _{I(HYST)}	Input hysteresis voltage			0.6		V
I _{IN}	Input current	$V_{IN} = V_{CC} = 32V$			300	μΑ

Table 7. Protections

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
T _{CSD}	Case shut-down temperature			125	130	135	°C
T _{CR}	Case reset temperature			110			°C
T _{CHYST}	Case thermal hysteresis			7	15		°C
T _{TSD}	Junction shutdown temperature			150	175	200	ှ င့
T _R	Junction reset temperature			135	77		°C
T _{HYST}	Junction thermal hysteresis			7	15		°C
I _{lim}	DC Short circuit current	$V_{CC} = 24V; R_{LOAD} = 10m\Omega$		0.7		1.7	Α
V _{demag}	Turn-off output clamp voltage	I _{OUT} = 0.5A; L = 6mH	_48	V _{CC} -57	V _{CC} -52	V _{CC} -47	V

Table 8. Status Pin

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{HSTAT}	High level output current	V_{CC} = 1832V; R_{STAT} = 1KΩ (Fault condition)	2	3	4	mA
I _{LSTAT}	Leakage current	Normal operation; V _{CC} = 32V			0.1	μΑ
V	Clamp valtage	I _{STAT} = 1mA	6.0	6.8	8.0	V
V _{CLSTAT}	Clamp voltage	I _{STAT} = -1mA		-0.7		V
50	lete F.					

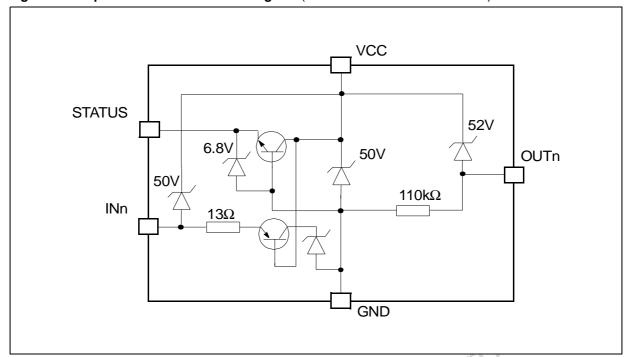
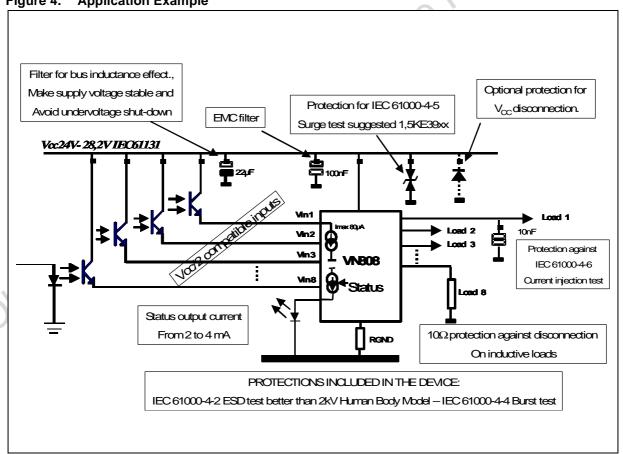


Figure 3. Equivalent Internal Block Diagram (same structure for all channel)

Figure 4. Application Example



Switching Time Waveforms

Figure 5. Turn-on & Turn-off

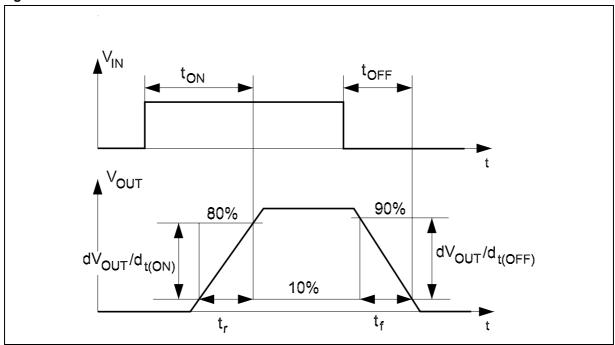
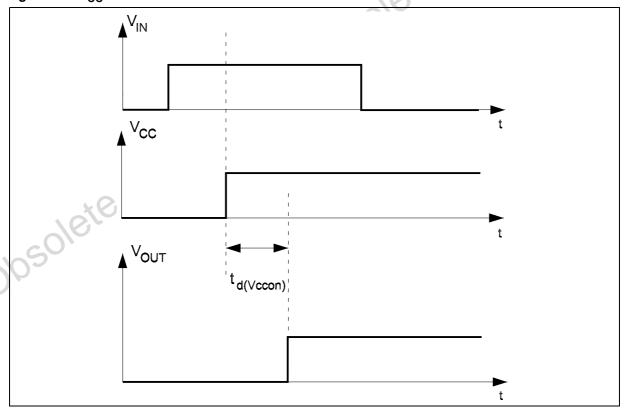


Figure 6. V_{CC} Turn-on



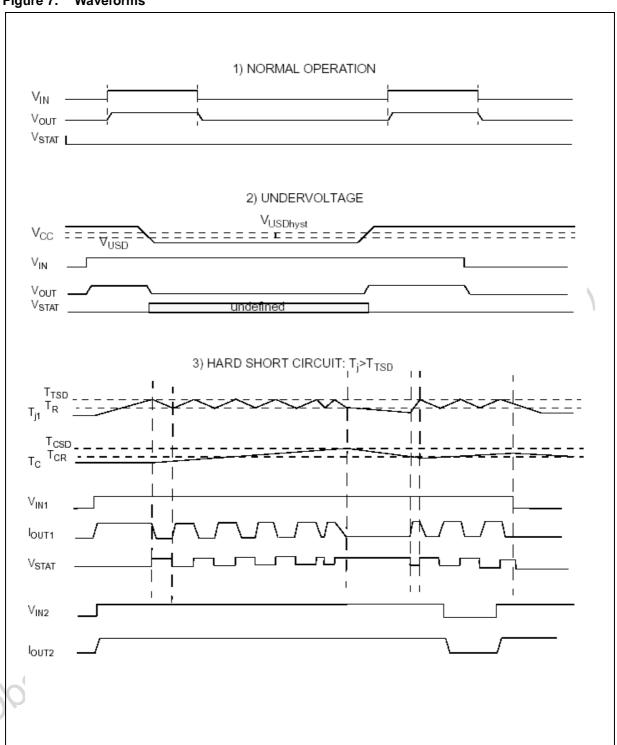
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Table 9. Truth Table

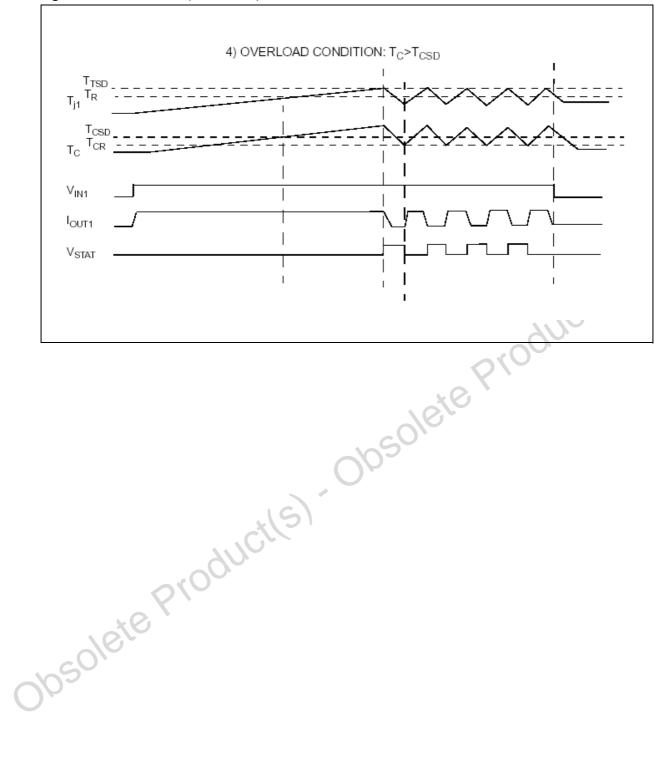
Conditions	INPUTn	OUTPUTn	STATUS
Normal operation	L	L	L
	H	H	L
Current limitation	L	L	L
	H	X	L
Overtemperature (see waveforms 3, 4 <i>Figure 7. Figure 8.</i>) -> $T_J > T_{TSD}$	L	L	L
	H	L	H
Undervoltage	L	L	X
	H	L	X



Figure 7. Waveforms







Mechanical Data

In order to meet environmental requirements, ST offers these devices in ECOPACK[®] packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

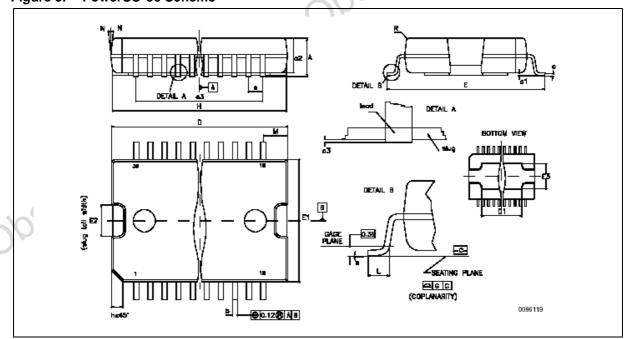


Table 10. PowerSO-36 Mechanical Data

DIM		mm.			inch	
DIM.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
Α			3.60			0.141
a1	0.10		0.30	0.004		0.012
a2			3.30			0.130
a3	0		0.10	0		0.004
b	0.22		0.38	0.008		0.015
С	0.23		0.32	0.009		0.012
D (1)	15.80		16.00	0.622		0.630
D1	9.40		9.80	0.370		0.385
E	13.90		14.50	0.547		0.570
E1 (1)	10.90		11.10	0.429		0.437
E2			2.90			0.114
E3	5.80		6.20	0.228		0.244
е		0.65			0.0256	
e3		11.05			0.435	
G	0		0.10	0		0.004
Н	15.50		15.90	0.610		0.626
h			1.10			0.043
L	0.80		1.10	0.031		0.043
N			10° (max)		
S				max)		

- 1. "D" and "E1" do not include mold flash or protusions
 - Mold flash or protusions shall non exceed 0.15mm (0.006 inch)
 - Critical dimensions are "a3", "E" and "G".

Figure 9. PowerSO-36 Scheme



VN808

Table 11. Order Codes

Package	Tube	Tape and Reel
PowerSO-36	VN808	VN80813TR

Obsolete Product(s).

Table 12. Revision History

Date	Revision	Changes
13-Sep-2005	4	Final release

Obsolete Product(s).

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